

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"6396148".pn. and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:00
L2	1	"5841193".pn. and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:13
L3	839	organic near3 quartz	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:09
L4	185	3 with (substrate carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:09
L5	2	"5841193".pn. and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:31
L6	1	"5291066".pn. and (cutting singulat\$3 electroplating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:22

L7	149	(US-20010003610-\$ or US-20030085466-\$ or US-20030101303-\$).did. or (US-3903590-\$ or US-4783695-\$ or US-4806409-\$ or US-4866501-\$ or US-4984059-\$ or US-5008614-\$ or US-5023202-\$ or US-5048179-\$ or US-5049980-\$ or US-5073814-\$ or US-5081563-\$ or US-5108825-\$ or US-5111278-\$ or US-5144747-\$ or US-5149662-\$ or US-5152054-\$ or US-5157589-\$ or US-5161093-\$ or US-5173766-\$ or US-5198385-\$ or US-5206712-\$ or US-5250843-\$ or US-5255431-\$ or US-5291066-\$ or US-5306670-\$ or US-5324687-\$).did. or (US-5336928-\$ or US-5338975-\$ or US-5345205-\$ or US-5353195-\$ or US-5353498-\$ or US-5359496-\$ or US-5366906-\$ or US-5378581-\$ or US-5384204-\$ or US-5422513-\$ or US-5432677-\$ or US-5434751-\$ or US-5452182-\$ or US-5455459-\$ or US-5527741-\$ or US-5559363-\$ or US-5564181-\$ or US-5565706-\$ or US-5606198-\$ or US-5629074-\$ or US-5657537-\$ or US-5703400-\$ or US-5719749-\$ or US-5745984-\$ or US-5757072-\$ or US-5818698-\$ or US-5821626-\$).did. or (US-5841193-\$ or US-5844304-\$ or US-5866952-\$ or US-5874770-\$ or US-5886401-\$ or US-5897337-\$ or US-5905303-\$ or US-5928838-\$ or US-5939214-\$ or US-5959357-\$ or US-5973927-\$ or US-5976912-\$ or US-5994771-\$ or US-5998859-\$ or US-6004867-\$ or US-6007668-\$ or US-6013948-\$ or US-6027791-\$ or US-6038133-\$ or US-6057593-\$ or US-6078104-\$ or US-6104089-\$ or US-6110806-\$ or US-6154366-\$ or US-6159767-\$ or US-6192579-\$ or US-6201299-\$).did. or (US-6214716-\$ or US-6215178-\$ or US-6228687-\$ or US-6229203-\$ or US-6229222-\$ or US-6239482-\$ or US-6239980-\$ or US-6242987-\$ or US-6271469-\$ or US-6274391-\$ or US-6294741-\$ or US-6300577-\$ or US-6306680-\$ or US-6313526-\$ or US-6320135-\$ or US-6326233-\$ or US-6332669-\$ or US-6344696-\$ or US-6350668-\$ or US-6388207-\$ or US-6388335-\$ or US-6388888-\$ or US-6395580-\$ or US-6396148-\$ or US-6400773-\$ or US-6403463-\$ or US-6407929-\$).did. or (US-6413700-\$ or US-6420664-\$	US-PGPUB; USPAT; DERWENT	OR	ON	2005/10/07 09:28
Search History 10/7/05 4:01:27 PM Page 2 C:\Documents and Settings\CPD\My Documents\EAST\Workspaces\%multilayer-tape-on-chips-sub-cavity.wsp (US-6413700-\$ or US-6420664-\$						

L8	2	"5745984".pn. and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:40
L9	61	("5745984").URPN.	USPAT	OR	ON	2005/10/07 09:33
L10	86	7 and (cutting singulat\$3 electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:42
L11	93	7 and ((substrate carrier) with (organic polymer\$2 polyimide plastic thermalplastic thermoplastic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 12:13
L12	54	11 and (cutting singulat\$3 electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:50
L13	85	11 and (cutting singulat\$3 separat\$3 electroplat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:17
L14	349379	"17" and (mems (mechanical near2 sensor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:18
L15	5	7 and (mems (mechanical near2 sensor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:20
L16	8	7 and (mems (mechanical near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:31

L17	8	7 and (mems ((mechanical electromechanical) near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:54
L18	2	"5874770".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:49
L19	3	"6614110".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:49
L20	862	waveguide with (mems ((mechanical electromechanical) near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 12:24
L21	340	waveguide near4 (mems ((mechanical electromechanical) near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:54
L22	254	waveguide near3 (mems ((mechanical electromechanical) near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:41
L23	29	22 and ((substrate carrier) with (organic polymer\$2 polyimide plastic thermalplastic thermoplastic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 12:24
L24	77	20 and ((substrate carrier) with (organic polymer\$2 polyimide plastic thermalplastic thermoplastic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:42

L25	48	24 not 23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 12:24
L26	48	25 and (mems ((mechanical electromechanical) near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 12:25
L27	35881	porous near3 (polyimide polymer\$2 plastic thermalplastic thermoplastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:39
L28	3	20 and 27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:39
L29	1286	27 and (mems ((mechanical microelectromechanical electromechanical) near2 (system sensor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:41
L30	504	29 and ((substrate carrier) with (organic polymer\$2 polyimide plastic thermalplastic thermoplastic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:42
L31	308	29 and ((substrate carrier) near3 (organic polymer\$2 polyimide plastic thermalplastic thermoplastic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:44
L32	3	"6800941".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:44

L33	1	32 and porous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:58
L34	1	"6274391".pn. and gold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:05
L35	1	"6396148".pn. and gold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:05
L36	1222	(method process) and ((substrate carrier pcb board) with (die chip) with (bump ball) with gold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:07
L37	724	(method process) and ((substrate carrier pcb board) with (die chip) with ((bump ball) near2 gold))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:07
L38	300	37 and @py<="2001"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:09
L39	21	7 and ((bump ball) near3 gold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:49